CHIPQUIK® **SMDSWLF.059 3.3 1LB**

Datasheet revision 1.2 www.chipquik.com

Solder Wire SAC305 No-Clean 0.059” (1.5mm) with 3.3% Flux Core 1lb Spool

Product Highlights

No-Clean Water-Washable Synthetic Flux Core
The clear, non-corrosive, non-conductive residue is meant to be left on the board. Residues that do remain are water soluble if you want to remove them. Clean with hot water at 60°C (140°F) minimum.
3.3% flux core
Halogen content: None
RoHS 3 and REACH compliant

Specifications

Alloy:	Sn96.5/Ag3.0/Cu0.5
Wire Diameter:	0.059” (1.5mm)
Flux Type:	No-Clean Water-Washable Synthetic
Flux Classification:	REL0
Melting Point:	217-220°C (423-428°F)
Packaging:	1 lb spool
Shelf Life:	>60 months

Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 3 Directive (EU) 2015/863:	Yes